

What is claimed is:

1. A semiconductor package for fixing a semiconductor element, comprising:

a substrate for mounting said semiconductor element thereon to fix the side of a surface where the element is formed of said semiconductor element to one side thereof, said substrate being provided with a through hall formed from the one side to the other side of the substrate; and

a connecting pattern provided on the other side of said substrate for electrical connection to said semiconductor element.

2. A semiconductor package as claimed in claim 1, wherein said connecting pattern is provided continuously in a plurality of stages and an end portion of said connecting pattern on the side of said through hall is provided on a stage on the side of the one side of said substrate.

3. A semiconductor package as claimed in claim 1, wherein said through hall is a plurality of through halls.

4. A semiconductor device with a semiconductor element fixed to a semiconductor package, said semiconductor package comprising:

a substrate for mounting said semiconductor element

thereon to fix said semiconductor element to one side thereof; and a connecting pattern provided on the other side of said substrate, said substrate being provided with a through hall formed from the one side to the other side of said substrate, wherein a surface where the element is formed of said semiconductor element is mounted on the one side of said substrate, an electrode of said semiconductor element is fixed to the one side so as to be within said through hall and is electrically connected to said connecting pattern via wires through said through hall, and said through hall and said wires are sealed with resin.

5. A semiconductor package as claimed in claim 4, wherein said connecting pattern is provided continuously in a plurality of stages and an end portion of said connecting pattern on the side of said through hall is provided on a stage on the side of the one side of said substrate.

6. A semiconductor package as claimed in claim 4, wherein said through hall is a plurality of through halls.

7. A method of manufacturing a semiconductor device with a semiconductor element fixed to a semiconductor package, comprising the steps of:

preparing said semiconductor package structured by

providing a substrate for mounting said semiconductor element thereon to fix said semiconductor element to one side thereof and a connecting pattern provided on the other side of said substrate and by forming a through hall from the one side to the other side of said substrate;

fixing a surface where the element is formed of said semiconductor element on the one side of said substrate of said semiconductor package such that an electrode of said semiconductor element is within said through hall;

electrically connecting said connecting pattern and said electrode of said semiconductor element via wires through said through hall; and

sealing said through hall and said wires with resin.

8. A method of manufacturing a semiconductor device as claimed in claim 7, wherein said connecting pattern is provided continuously in a plurality of stages and an end portion of said connecting pattern on the side of said through hall is provided on a stage on the side of the one side of said substrate.

9. A method of manufacturing a semiconductor device as claimed in claim 7, wherein said through hall is a plurality of through halls.

10. A method of manufacturing a semiconductor device as

claimed in claim 7, 8, or 9, wherein the surface where the element is formed of said semiconductor element is fixed on the one side of said substrate of said semiconductor package via a tape-like bonding material.

11. A method of manufacturing a semiconductor device as claimed in claim 7, 8, or 9, wherein the surface where the element is formed of said semiconductor element is fixed on the one side of said substrate of said semiconductor package with adhesive.